EFFECT OF O₂ PARTIAL PRESSURE ON YBa₂Cu₃O₇–δ THIN FILM GROWTH BY PULSED LASER DEPOSITION

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YBa$_2$Cu$_3$O$_{7-\delta}$ thin films were processed by pulsed laser deposition on (1 0 0) LaA10$_3$ substrates using O$_2$ partial pressures from 120 to 1200 mTorr. The effect of O$_2$ pressure on film properties including room temperature resistivities and microstructures was studied for a unique set of deposition parameters. The film quality was observed to remain high over a wide range of O$_2$ partial pressures, with much less sensitivity to O$_2$ pressure than previous studies which are compared. For O$_2$ pressures from 200 to 1200 mTorr, superconducting transition temperatures consistently reached values >91.5 K and transport critical current densities were 3-5 MA/cm$^2$ (77 K, self-field). It is proposed that less sensitivity of film properties to O$_2$ pressure is achieved by: (1) reducing the particle velocity of the plume below a critical threshold, and (2) using a deposition temperature of 785 °C for adequate surface activation.
Effect of O$_2$ partial pressure on YBa$_2$Cu$_3$O$_{7-\delta}$ thin film growth by pulsed laser deposition

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Abstract

YBa$_2$Cu$_3$O$_{7-\delta}$ thin films were processed by pulsed laser deposition on (1 0 0) LaAlO$_3$ substrates using O$_2$ partial pressures from 120 to 1200 mTorr. The effect of O$_2$ pressure on film properties including room temperature resistivities and microstructures was studied for a unique set of deposition parameters. The film quality was observed to remain high over a wide range of O$_2$ partial pressures, with much less sensitivity to O$_2$ pressure than previous studies which are compared. For O$_2$ pressures from 200 to 1200 mTorr, superconducting transition temperatures consistently reached values >91.5 K and transport critical current densities were 3–5 MA/cm$^2$ (77 K, self-field). It is proposed that less sensitivity of film properties to O$_2$ pressure is achieved by: (1) reducing the particle velocity of the plume below a critical threshold, and (2) using a deposition temperature of 785 °C for adequate surface activation.

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Keywords: YBa$_2$Cu$_3$O$_{7-\delta}$; Oxygen pressure; Pulsed laser deposition; HTS thin films

1. Introduction

The growth of YBa$_2$Cu$_3$O$_{7-\delta}$ (YBCO) thin films is of great interest for superconducting applications such as AC wires, generators, or motors operating at 77 K, because of the excellent critical current densities ($J_c$) and intrinsic pinning properties of YBCO in magnetic fields [1]. Recently, the development of coated conductor wire technologies for aligning YBCO grains on metallic substrates with $J_c > 1$ MA/cm$^2$ has stimulated further interest in understanding and improving YBCO thin film deposition techniques [2–4]. One of these techniques of interest for coated conductor development is pulsed laser deposition [5]. While the studies herein were performed on LaAlO$_3$ single crystals, the lattice mismatch and other properties of LaAlO$_3$ are similar to buffer layer materials such as CeO$_2$ used as final buffer layers on biaxially textured metallic substrates. Therefore it is expected that the work herein can also be applied for coated conductors, as well as work that requires deposition on single crystal substrates.
Pulsed laser deposition (PLD) is a well-known method for depositing YBCO thin films with generally excellent properties. Although PLD of YBCO has been studied extensively, there are many factors that are yet unknown. The parameter space for PLD includes many variables such as substrate temperature, O₂ pressure during deposition, target-to-substrate distance; laser properties including fluence, wavelength, beam profile uniformity and repetition rate; target properties including density and optical absorption; ablation footprint size and dimensions (which affect plume shape); and substrate parameters such as chemical composition and lattice constant matches. These parameters are interrelated and optimization for one parameter can involve a range of optimization for others.

The role of oxygen pressure in pulsed laser deposition of YBCO was studied early on after the introduction of the high temperature superconductors, and has received renewed attention recently with the development of the coated conductor technology [5–14]. In addition to affecting parameters discussed above, varying the oxygen deposition pressure during PLD can influence film growth by changing the ionic ratios of the plume [5,6], altering the chemical species during deposition [5], and varying the crystallization temperature of the deposited compound. Up to 1994, O₂ pressures were typically studied from about 50 to 400 mTorr, and the best deposition conditions were achieved within this range [5,7]. Recently, however, there is increasing evidence that excellent properties can be achieved at higher O₂ pressures of 100–800 mTorr [8–11]. However in studies thus far, a narrow window of O₂ pressure existed where an optimal \( T_c \) and \( J_c \) could be obtained [7–11].

This work extends the study of O₂ deposition pressures ranging from 120 to 1200 mTorr, and results are compared to previous studies on effects of O₂ pressure. Previously, all data supported the supposition that a narrow window of O₂ pressure was required to achieve optimal film quality [7–14], and both microstructural and transition data indicated good film quality could only be obtained with the plume just touching the substrate [12–14]. To model the dependence on O₂ pressure, it was observed that at lower substrate temperature, a relation between target-to-substrate distance (\( D \)) and O₂ pressure (\( P \)) existed with \( PD^{n(1-n)} = \text{const} \sim \text{particle velocity} \), and \( n \) is a constant in the range of 0.4–0.6 that fits the experimental \( P-D \) data [7]. For any value of \( D \) chosen, a very narrow range of O₂ pressure was required to maintain a constant velocity of particle bombardment. The particle bombardment presumably increased the surface activation and enabled film growth at lower temperatures [7]. The results in this paper at higher substrate temperature, however, provide substantial evidence that cannot be explained with this model, and indicates that different mechanisms must be considered for film growth. Herein, both microstructural and transport properties were optimized in a very wide range of pressure (200–1200 mTorr). With the plume length (\( L_p \)) extending to touch the substrate only at 600 mTorr, optimum results were obtained with the substrate located both inside and outside of the plume; \( D/L_p \approx 0.7–1.2 \). These results are explained as a consequence of several film growth mechanisms.

2. Experimental

Parameters used for pulsed laser deposition are described in Table 1. The YBCO powder in the target was prepared by chemical precipitation with submicron size (nominally 99.999% pure) [15]. Films were deposited in a spherical-shaped vacuum chamber (~20 cm diameter) with a 5 cm diameter substrate heater [16]. The temperature of the heater block is reported herein, measured with K-type thermocouples placed in contact with the heater block directly behind where the samples were mounted. The standard measurement error for K-type thermocouples is 0.75% for temperatures >300 °C (Omega Engineering Inc., Stamford, CT). An excimer laser (Lambda Physik, model LPX 305i) operating at the KrF wavelength was used. LaAlO₃ single crystal substrates were provided by the manufacturer epitaxially polished on both sides, and were attached to the heater using a thin layer of colloidal Ag paint. The oxygen deposition pressure was measured with capacitance
manometer and convectron gauges with <1% variation. Oxygen gas (99.999% purity) flowed into the chamber during growth at \( \sim 1 \) l/min, and the oxygen pressure in the chamber was kept constant in the chamber using a downstream throttle-valve control on the pumping line. The YBCO target was resurfaced periodically with SiC sandpaper, and conditioned with \( \sim 3000 \) laser pulses using a laser fluence of 2–4 J/cm\(^2\) prior to deposition. The target rotated during deposition and the laser beam was scanned across 1.5 cm of the 5 cm diameter target. Scanning the target allowed more uniform wear of the target and provided a larger area of deposition. The plume varied only slightly as a consequence of scanning. The LaAlO\(_3\) (1 0 0) single crystal substrates were ultrasonically cleaned for 2 min each using first acetone, followed by dehydrated ethyl alcohol.

The background pressure in the chamber was reduced to \(<10^{-6}\) Torr prior to deposition. Samples were heated from room temperature to deposition temperature of 785 °C at 1270 °C/h. Film thickness was controlled by varying the deposition time. After deposition, films were cooled from 785 to 750 °C at 1270 °C/h before turning off the vacuum pumps and O\(_2\) pressure control. Subsequently the O\(_2\) flow was increased to \( \sim 1.5 \) l/min into the chamber. The films were then cooled from 750 °C to 500 °C at a rate of 1270 °C/h, and held at 500 °C for 30 min, during which the O\(_2\) pressure reached 1 atm. The films were cooled from 500 °C to 250 °C at about 1250 °C/h, and from 250 °C to room temperature using the natural cooling rate of the heater block (\( \sim 800 \) °C/h).

After deposition, current and voltage contacts were patterned onto the films by DC magnetron sputter deposition of Ag with \( \sim 3 \) µm thickness. The current contacts covered the sample ends (\( \sim 2 \) mm on each end), and the voltage contacts were separated from the current contact, with a size of \( \sim 2 \) mm\(^2\) and centered about 0.5 cm apart. The resistance of the Ag contacts was reduced by annealing in pure O\(_2\) at 550 °C for 30 min with heating and cooling rates of 200 °C/h [17]. The non-Ag coated areas of the films were patterned to make macrobridges 0.3 cm long and 0.048 cm wide, using 248 nm KrF laser etching through a precisely machined Al\(_2\)O\(_3\) mask. The laser parameters for etching were fluence of 0.1–0.2 J/cm\(^2\), 1–2 Hz repetition rate, and number of pulses 100–1000 depending on film thickness.

Transport critical current density \( (J_c) \) measurements were made in liquid nitrogen at 77.2 K with the 4-pt probe method (self-field) using pogo

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**Table 1**

Pulsed laser deposition parameters for work herein and other studies

<table>
<thead>
<tr>
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<tbody>
<tr>
<td>Laser wavelength (nm)</td>
<td>248</td>
<td>193</td>
<td>248</td>
<td>308</td>
<td>248</td>
<td>308</td>
</tr>
<tr>
<td>Laser pulsewidth (ns)</td>
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<td>15</td>
<td>25</td>
<td>30</td>
<td>25</td>
<td>25</td>
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<tr>
<td>Pulse energy (mJ)</td>
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<td>–</td>
<td>45</td>
<td>93</td>
<td>104</td>
<td>103</td>
</tr>
<tr>
<td>Ablation spot size (mm(^2))</td>
<td>( \sim 1 \times 6.3 )</td>
<td>–</td>
<td>( \sim 1 \times 4.5 )</td>
<td>5.45</td>
<td>( \sim 2 \times 4 )</td>
<td>5</td>
</tr>
<tr>
<td>Laser fluence (J/cm(^2))</td>
<td>3.2</td>
<td>3</td>
<td>1</td>
<td>1.7</td>
<td>1.3</td>
<td>2.1</td>
</tr>
<tr>
<td>Repetition rate (Hz)</td>
<td>4</td>
<td>–</td>
<td>5</td>
<td>4</td>
<td>10</td>
<td>10</td>
</tr>
<tr>
<td>Target-to-substrate distance (cm)</td>
<td>6</td>
<td>6</td>
<td>6</td>
<td>4.5</td>
<td>6.5</td>
<td>3.5</td>
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<tr>
<td>Laser strike angle (° from target normal)</td>
<td>45</td>
<td>–</td>
<td>–</td>
<td>–</td>
<td>45</td>
<td>45</td>
</tr>
<tr>
<td>Target density (%)</td>
<td>92</td>
<td>–</td>
<td>–</td>
<td>85</td>
<td>High</td>
<td>75</td>
</tr>
<tr>
<td>Substrate</td>
<td>LaAlO(_3)</td>
<td>MgO</td>
<td>LaAlO(_3), SrTiO(_3), MgO</td>
<td>LaAlO(_3)</td>
<td>SrTiO(_3)</td>
<td></td>
</tr>
<tr>
<td>Substrate size (mm(^3))</td>
<td>( 12 \times 3.2 )</td>
<td>( 5 \times 0.5 )</td>
<td>( 10 \times 10 )</td>
<td>–</td>
<td>( 15 \times 15 ) ( \sim 1.3 \times 1.3 )</td>
<td></td>
</tr>
<tr>
<td>Substrate temperature (°C)</td>
<td>785</td>
<td>680</td>
<td>780 LaAlO(_3), 800 MgO</td>
<td>750</td>
<td>770</td>
<td>725</td>
</tr>
<tr>
<td>Film thickness (µm)</td>
<td>0.2–0.8</td>
<td>–</td>
<td>0.1–0.2</td>
<td>–</td>
<td>( \sim 0.3 )</td>
<td>–</td>
</tr>
<tr>
<td>O(_2) in situ anneal</td>
<td>500 °C, 760 Torr</td>
<td>–</td>
<td>550 °C, flowing O(_2), 700 °C, 760 Torr</td>
<td>–</td>
<td>–</td>
<td>–</td>
</tr>
</tbody>
</table>
pins for current contacts [17,18], and a 1 μV/cm criterion. The temperature of liquid N\textsubscript{2} was measured with a Lakeshore 340 Temperature Controller and different Cernox\textsuperscript{TM} RTD sensors calibrated by the manufacturer using NIST traceable standards. Current was applied to the sample by a step-ramp method: a current step interval of 0.2–0.5 s, a ramp rate of 0.25–1.0 A/s, and a voltage sample period 2–4 times smaller than the current step interval. The maximum current step size was 0.2 A. Measurements of \( J_c \) were repeatable for these ranges of step-ramp parameters. Current and voltage sources for resistivity and critical current measurements were calibrated on a regular basis. The film thickness was measured with a Tencor P10 stylus profilometer in areas of the LaAlO\textsubscript{3} substrates free of microcrystalline undulations, and with SEM on fractured cross-sections. The thickness of every sample was measured in areas near/or on the bridge areas across step-edges created by etching with \( \sim 4\% \) volume fraction HNO\textsubscript{3} acid. Acid etching had no measurable effect on the LaAlO\textsubscript{3} substrates, however, was able to quickly etch the film in only about 10 s. For room temperature resistivity measurements, care was used to remove all excess film and Ag paint on the sample sides and bottom with sandpaper or dilute HCl etch.

The superconducting transition temperature (\( T_c \)) was measured using an AC susceptibility technique with the amplitude of the magnetic sensing field, \( h \), varied from 0.025 to 2.2 Oe, at a frequency of approximately 4 kHz [19,20]. Note that the AC susceptibility technique provides information about primary and secondary transitions of the entire film, rather than a defined path that is obtained with transport \( T_c \) measurements. Transition widths and peak shifts of the loss coefficient (\( \chi'' \)) for varying \( h \) can give a qualitative measure of the intergrain coupling and \( J_c \) [19,20]. The AC susceptibility technique has the advantage of measuring \( T_{cs} \) of films non-destructively as deposited without any effect from Ag metallization or etching. Herein, \( T_{cs} \) were measured immediately after film deposition and prior to adding Ag contacts.

For \( T_c \) measurements, samples were mounted onto the end of a sapphire rod with a GaAlAs temperature sensor embedded in the rod. The sapphire rod was held in a cryogenic dewar filled with gaseous He evaporated from the liquid. Samples were measured as the He gas was warmed from 4.2 K. The warming rate in the transition region was very slow at \( \sim 0.06 \) K/min, which provided a stable and reproducible measurement. The \( T_c \) transition was measured at 0.03 K increments. The GaAlAs temperature sensor was accurate within \( \leq 0.1 \) K at three calibration points: liquid He at 4.2 K, liquid N\textsubscript{2} at 77.2 K, and room temperature.

3. Results

The effect of varying O\textsubscript{2} deposition pressure on plume characteristics is shown in Fig. 1. As the O\textsubscript{2} pressure was increased, the plume reduced in width and length as expected from increased collisional dampening [5]. The visible part of the plume just reached the substrate at an O\textsubscript{2} pressure of 600 mTorr. For a lower deposition pressure (120–200 mTorr), the plume was quite broad and deposited the target material over a cross-sectional area of about 6 cm diameter. The plumes were approximately spherical shaped (width/length \( \sim 0.9 \)), and uniform and soft around the edges. The spherical-shaped plume is in contrast with most previous reports with more forward-directed plumes [5,12,13]. Fig. 1 also shows a transition from yellowish to reddish color in the outer edge of the plume, as the oxygen pressure was increased. This visible red emission corresponds to increased formation of YO [6].

As the O\textsubscript{2} chamber pressure was varied, the deposition rate was changed as shown in Fig. 2. The trend of higher deposition rate when the plume edge touches the substrate is consistent with previous work [10]. For O\textsubscript{2} pressure < 600 mTorr, the plume impinged on the substrate, which may increase the possibility for re-sputtering resulting from bombardment of high energy particles in the plume. For O\textsubscript{2} pressure > 600 mTorr, the plume is more focused which increases the localized deposition.

A plot of the superconducting transition of a representative film with \( T_c \sim 92 \) K is given in
Fig. 3. The onset of the transition is quite high at 92.0 K, reaching nearly the maximum for the YBa$_2$Cu$_3$O$_{7-y}$ compound of 92.6 K [21]. For 0.025 Oe applied AC field, the FWHM width of the $\chi''$ peak was <0.2 K. The shift of the $\chi''$ peak maximum as $h$ was varied from 0.025 to 2.2 was $\sim$0.9 K. Similar shifts of the $\chi''$ peak as small as 0.65 K were observed for films with $T_c > 91.5$ K. Such narrow transitions and peak shifts as measured by AC susceptibility generally indicate the film has excellent uniformity and intergrain coupling and a high transport $J_c$ (>1 MA/cm$^2$ at 77 K) [19,20].

Fig. 4 plots the $T_c$ onset for films deposited with varying O$_2$ pressure, and compares the results with $T_c$s from previous studies measured by both AC susceptibility and transport currents [7–11]. The comparison of $T_c$s measured by different methods is meaningful, as $T_c$s measured by AC susceptibility usually correspond to within 1 K to the zero-resistance point of a transport measurement [10]. The $T_c$s in Fig. 4 showed a gradual increase from $\sim$88 to >91.5 K as the O$_2$ pressure was increased from 120 to 400 mTorr. For O$_2$ pressure from 400 to 1200 mTorr, the $T_c$s were very high and consistent at 91.8 ± 0.4 K for multiple deposition runs.
and for all samples in these runs without exception. Typically, high $T_c$s of ~90–91 K are usually reported for YBCO thin films, regardless of the deposition method [5].

The trend in Fig. 4 of constant $T_c$ for a wide range of $O_2$ pressures from 400 to 1200 mTorr varies from other studies where maximum $T_c$s were obtained for narrower windows of $O_2$ pressure [7–11]. The variation of results in Fig. 4 indicates the potentially subtle effect of different growth conditions (Table 1) on $T_c$ and film properties. The most distinctly different result presented in Fig. 4 was from a study in which a low growth temperature of 680 °C was chosen along with MgO as a substrate [7]. Another study found only small differences between MgO and LaAlO$_3$ for growth at 700–840 °C [8]. Therefore, the lower growth temperature of 680 °C combined with a highly energetic plume might presumably be the dominant factors for reducing the sensitivity to $O_2$ pressure for Ref. [7].

Results in Fig. 4 can be compared to $T_c$s of films quenched from the deposition temperature for varying $O_2$ pressure [14]. In [14], $T_c$s from previous studies were included for comparison: (●) [7]; (+) [8]; (□) [9]; (○) [10] and (●) [11]. $T_c$s from previous studies were measured by the resistive method [7,8], by AC susceptibility [9,10], and by an unspecified method [11]. Lines are guides to the eye.

Fig. 5 plots transport $J_c$ by the four-probe method as a function of $O_2$ deposition pressure, and compares it to results from a similar study.
For O$_2$ pressure from 200 to 1200 mTorr, $J_{cs}$ were consistently at 3–5 MA/cm$^2$ as measured at 77.2 K in self-field. The spread of $J_{cs}$ in Fig. 5 for a given O$_2$ pressure results mostly from the dependence of $J_c$ on film thickness, as given in Fig. 6 for films deposited for different O$_2$ pressure ranges.

As seen in Fig. 5, transport $J_c$ had a slightly different dependence on O$_2$ pressure than $T_c$. For example, at 200 mTorr $J_c$s were high, whereas $T_c$s were in the range of 89–92 K. When the substrates were located outside of the plume for O$_2$ pressure $>$900 mTorr, $J_c$s showed a slight decrease to about 3 MA/cm$^2$, even though the $T_c$s were consistently near 92 K. The decrease in $J_c$ for O$_2$ pressure $>$900 mTorr might be correlated with increasing surface roughness, as films deposited at these pressures appeared grayish to the eye, and the surfaces as viewed by SEM contained high densities of micron-size particulates (also shown later in this paper).

The effect of O$_2$ deposition pressure on the room temperature resistivity ($\rho$) of films represented in Fig. 5 is given in Fig. 7. The resistivity had a different dependence on O$_2$ pressure than $T_c$ or $J_c$, with the lowest values of resistivity obtained at O$_2$ pressure about 200–400 mTorr. The change in resistivity in Fig. 7 is not related to the $J_{cs}$ in Fig. 5, as there was only a small correlation of resistivity with $J_c$, as shown in Fig. 8. In Fig. 8, higher $J_c$s were slightly correlated with higher room temperature resistivity, although the relationship was not very strong.

The microstructures of films deposited at different O$_2$ pressures are shown in Fig. 9. Films deposited at 120 mTorr had a high concentration of pinhole defects which may have been caused by selective resputtering from the very high translational kinetic energy particles in the plume (up to 50 eV) [22], or reduced ripening of island growth at lower deposition rates [5]. Films deposited at
1200 mTorr showed a high concentration of surface particulates, which may be related to the formation of YBCO nanoparticles in the vapor phase that can attach to the surface with low concentration and form nucleation centers for undesired growth [23].

The precise reason why $T_c$ and $J_c$ were decreased at lower O$_2$ pressures has not been fully answered yet. The oxygen content of the films as measured by XRD was constant for all O$_2$ deposition pressures. The average oxygen content was $6.96 \pm 0.02$, using the formula $X = 77.085 - 6.015D$ where $X$ is the oxygen content and $D$ is the average lattice spacing in Angstroms [24]. However, films deposited at different O$_2$ pressures showed distinct differences in impurity content. A film deposited at 120 mTorr had detectable (albeit minute) amounts of Al, Fe and Cr impurity in it as measured by SIMS, unlike one deposited at 600 mTorr. The increase in impurity content could presumably come from interaction (and sputtering) of the plume with the heater block and support structures (Fig. 1). The heater block did show evidence

![Fig. 8. Correlation of transport $J_c$ and room temperature resistivity of films for films deposited at 120 mTorr (O) and 200–600 mTorr (●). Lines are linear fits with correlation coefficients $R = 0.80$ (O) and $R = 0.28$ (●).](image)

![Fig. 9. SEM micrographs at 5000× magnification of YBCO film surfaces for varying O$_2$ deposition pressure.](image)
Mechanism (2): The particle velocity at the substrate must remain below a critical value, to prevent high velocity particle bombardment which results in degradation of $T_c$ and $J_c$. This supposition is consistent with the $P$–$D$ model for less-than-ideal $O_2$ pressures. Optimum growth occurred herein for $D/L_p \approx 0.7$–1.2, and degradation was observed only for $D/L_p \sim 0.6$, when the substrate was located closer to the center of the plume. The velocity of the plume shock front decreases as it expands into partial $O_2$ pressure typically as expected from a simple Beer’s law model of scattering $I = I_0 e^{-x}$, where $I$ is the integrated ion–probe current, $N$ is the pressure, $x$ is the distance and $\sigma$ is the generalized cross-section $\approx 2 \times 10^{-16}$ cm$^2$ for ion oxygen collisions [5,25]. As the $O_2$ pressure is increased from 50 to $\sim$300 mTorr, the plume experiences increased collisions and decreases in velocity for a given distance $D$ from the target. The decrease of particle velocity is consistently observed, as measured by integrated ion–probe current drops, and for varying laser fluence by optical spectroscopy of time-of-flight (TOF) emission profiles and electronic temperatures [5,25,26]. Specifically for similar conditions as this work (3.0 J/cm$^2$ fluence and 248 nm irradiation), the average particle velocity decreased by $\sim$60% as the $O_2$ pressure was increased from 100 to 200 mTorr for $D = 5$ cm [5,25]. We propose that for the plume and substrate conditions in this work ($D/L_p \sim 0.6$, 120 mTorr) the particle velocity exceeded a critical value, above which film degradation occurred.

An interesting subtlety exists for deposition at higher $O_2$ pressure; however, which should be considered to explain the results herein and differences with other studies in Figs. 4 and 5. For $O_2$ pressure $\sim$600 mTorr and higher, the temperature and particle velocity inside the plume ($D/L_p \sim 0.4$–0.75) was observed to increase for fixed $D$ positions, as the plume energy became increasingly restricted to a smaller region with higher $O_2$ pressure [26]. This velocity increase in the center region of the plume was easily observed from real-time camera imaging of the plume, especially for 1200 mTorr velocity, and was consistently measured for different laser fluence using TOF spectra and thermal spectroscopy for varying laser fluence as the pressure was increased from $\sim$600 to
1200 mTorr [26]. Therefore, we believe placement of the substrate in the plume is also an important contributing factor to give the non-sensitivity to O$_2$ pressure as shown herein. For higher pressures and unknown particle velocities, it might be considered safest to position the substrate near or beyond the plume edge ($D/L_p > \sim 0.8$), where the particle velocity experiences a sharp gradient drop in temperature and velocity to reach thermal equilibrium beyond the plume edge ($D/L_p > 1.0$). These conditions were satisfied for the work herein. In contrast, if the substrate is placed near the center of the plume ($D/L_p \sim 0.5$), at higher pressures the substrate can be exposed to increasing particle velocities as the O$_2$ pressure is increased. This mechanism may explain why plots from Refs. [8–10] in Fig. 4 for $\sim 780$ °C substrate temperature have decreased $T_c$ at higher-than-optimal O$_2$ pressure, in contrast with results from this work.

The role of laser fluence was not fully explored in this paper. With higher energy deposited $E_0$, the plume extends further and the particle velocities are higher inside the plume; for the blast wave model the shock front velocity $\sim \text{const} \times (E_0/\rho_0)^{1/3} r^n$, where $\rho_0$ is the gas pressure, $t$ is time, and $n$ is a constant that models the distance versus time experimental data of the plume expansion front [5,25]. Therefore for higher fluences, one would expect that the substrate should be placed further towards the plume edge ($D/L_p > 0.6$ for our conditions) to avoid damaging particle velocities. Preliminary experiments varying the fluence to move the substrate location in the plume were consistent with this consideration and the mechanisms above. At 300 mTorr, the laser fluence was varied from 2.2 to 3.2 J/cm$^2$ ($D/L_p \sim 0.8$–1.0) by increasing the laser energy, and the $T_c$s and $J_s$s were not greatly affected. At 1200 mTorr, the plume was extended by changing the focusing optics to narrow the beam considerably ($D/L_p \sim 0.8$), or increasing the fluence to 4.5 J/cm$^2$ by increasing the laser energy ($D/L_p \sim 1.1$), and for both of these cases there was no effect on $T_c$s or $J_s$s (see Fig. 5 for higher fluence).

It should also be noted that in the work herein, the window of optimized deposition included a large region from 200 to 600 mTorr when the substrate was located inside the plume ($D/L_p \sim 0.7$–1.0). This result is in contrast with previous results, where films deposited at $D/L_p \sim 0.7$ contained very large and well-separated grains and lower $J_c$ [12], and optimized results were obtained at the plume edge $D/L_p \sim 1.0$. We believe this is also a consequence of the optimized particle velocity for these O$_2$ pressures, as discussed above.

5. Conclusions

High quality YBCO films were deposited for a wide range of O$_2$ deposition pressure, with the substrate located both inside and outside of the plume ($D/L_p \sim 0.7$–1.2). $T_c$s $> 91.5$ K and excellent four-probe transport $J_s$s of 3–5 MA/cm$^2$ at 77 K in self-field, were consistently and reliably obtained for O$_2$ pressures from 200 to 1200 mTorr. The films always had a mirror-like surface finish when grown inside the plume (O$_2$ pressure $\leq 600$ mTorr, $D/L_p \sim 0.6$–1.0). Room temperature resistivities, $T_c$s, $J_s$s and microstructures all had slightly varying dependence on O$_2$ pressure. The relative insensitivity to O$_2$ pressure is proposed to be a consequence of two mechanisms: (1) growth at 780 °C does not require additional surface activation from particle bombardment, and (2) the velocity of particle bombardment must be reduced below a critical threshold value to prevent degradation of film properties; for the conditions of this study the substrate was placed near-or-beyond the plume ($D/L_p > 0.7$). We believe this is the first report where $T_c$s at 92 K and $J_s$s from 3–5 MA/cm$^2$ have reliably and repeatably been obtained in YBCO thin films for a wide range of O$_2$ deposition pressures. The relative insensitivity of $T_c$ and $J_c$ to O$_2$ pressure for the conditions studied will provide useful information for any PLD optimization and scale-up.

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